

ABSTRACT OF THE DISCLOSURE

The invention encompasses methods of preparing interposers for utilization in semiconductor packages. The invention includes a method in which an interposer substrate having a surface and a conductive layer extending over the surface is provided. Pads are formed on the conductive layer by plating a conductive material on the conductive layer while using the conductive layer as an electrical connection to a power source and without utilizing conductive busses, other than the conductive layer. Subsequent to the formation of the pads, the conductive layer is patterned into circuit traces. Methodology of the present invention can be utilized for, for example, forming board-on-chip constructions.